

**INFORMATION DISCLOSURE
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First Named Inventor	Fuller, Edward Nelson
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Examiner Name	Rost, Andrew J.
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Examiner Initials*	Cite No.	Patent Number	Kind Code ¹	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1	US-7372074		5/13/2008	Milne et al.	

NON-PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.		
	1	Gui, C. et al, "Selective Wafer Bonding by Surface Roughness Control", Journal of The Electrochemical Society, 148 (4) G225-G228 (2001)	T5
	2	Gui, C. et al., "Fusion bonding of rough surfaces with polishing technique for silicon micromachining", Microsystem Technologies (1997) 122-128	
	3	Zhixiong Liu et al., "Micromechanism fabrication using silicon fusion bonding", Robotics and Computer Integrated Manufacturing 17 (2001) 131-137	

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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